

- ☞ L50: (628917) L48 L49
- ☞ L51: (7017582) 47 50
- ☞ L52: (420) 43 with 10
- ☞ L53: (11) 25 and 52
- ☞ L54: (2111) 12, ii.
- ☞ L55: (6) 54 and 52
- ☞ L56: (12) 53 55
- ☞ L57: (598939) 18 18
- ☞ L58: (204646) 43 with 51
- ☞ L59: (5224) 58 with 57
- ☞ L60: (6585) 54 25
- ☞ L61: (8606) 60 26
- ☞ L62: (13) 59 and 61
- ☞ L63: (17063) reflow with solder
- ☞ L64: (18) 61 and 63
- ☞ L65: (132) 61 and 23
- ☞ L66: (34263) reflow
- ☞ L67: (202658) solder
- ☞ L68: (38) 65 and 67
- ☞ L69: (9) 85 and 88
- ☞ L70: (712766) bump ball flip adj chip adj bond \$4
- ☞ L71: (9486) 70 with 23
- ☞ L72: (21) 61 and 71
- ☞ L73: (1) Forward citation search 2
- ☞ L74: (1) Backward citation search 2

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65 and 66

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